

Military and Aerospace FPGA and Application Meeting

**Nov. 27 – 29, 2007
Palm Beach, FL**

Intermittency Detection and Mitigation in FPGAs

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Ridgetop Group, Inc.**

**Innovative Detector:
Faults in Solder-Joint Pins of
Fully Programmed and Operational
Field Programmable Gate Arrays
(FPGAs)**

**SJ BIST™
Verilog softcore in FPGA**

**SJ Monitor™
IC Chip on Same Board as FPGA**

(Patents pending)

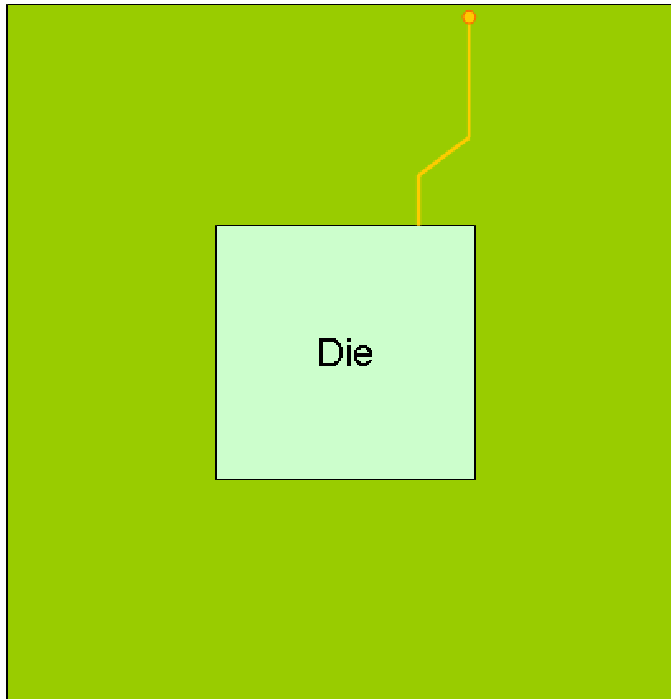
Topics:

- 1. State of the Art: packaging, mounting and soldering, cracks and fractures, intermittency, high stress areas, I/O ports**
- 2. SJ BIST: description, cap-R-freq, test results, HALT experiments, demonstration box**
- 3. SJ Monitor: description, signals, tests: temperature, voltage, power, detectable fault resistance**
- 4. SJ BIST deliverables**
- 5. SJ Monitor status**

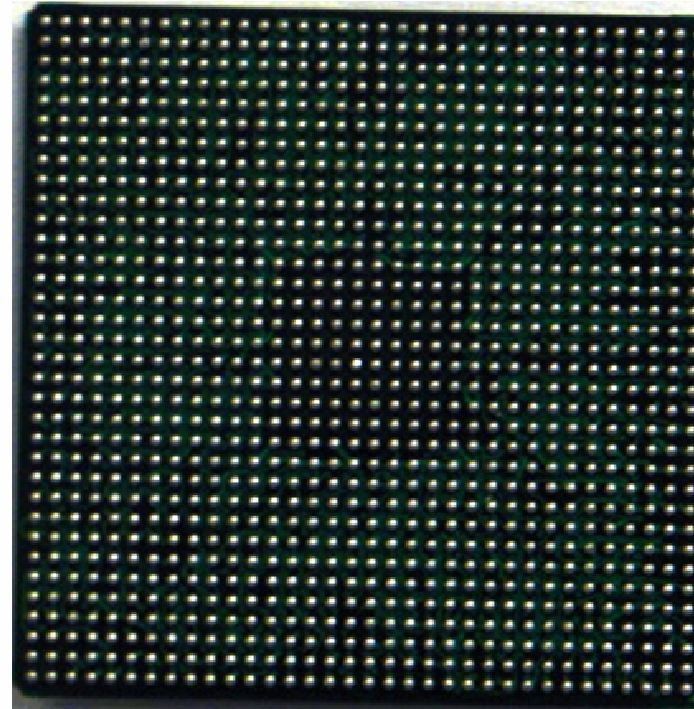
State of the Art: Packaging

- Problematic visual, optical, x-ray ... inspection techniques
 - small pitch, small ball sizes

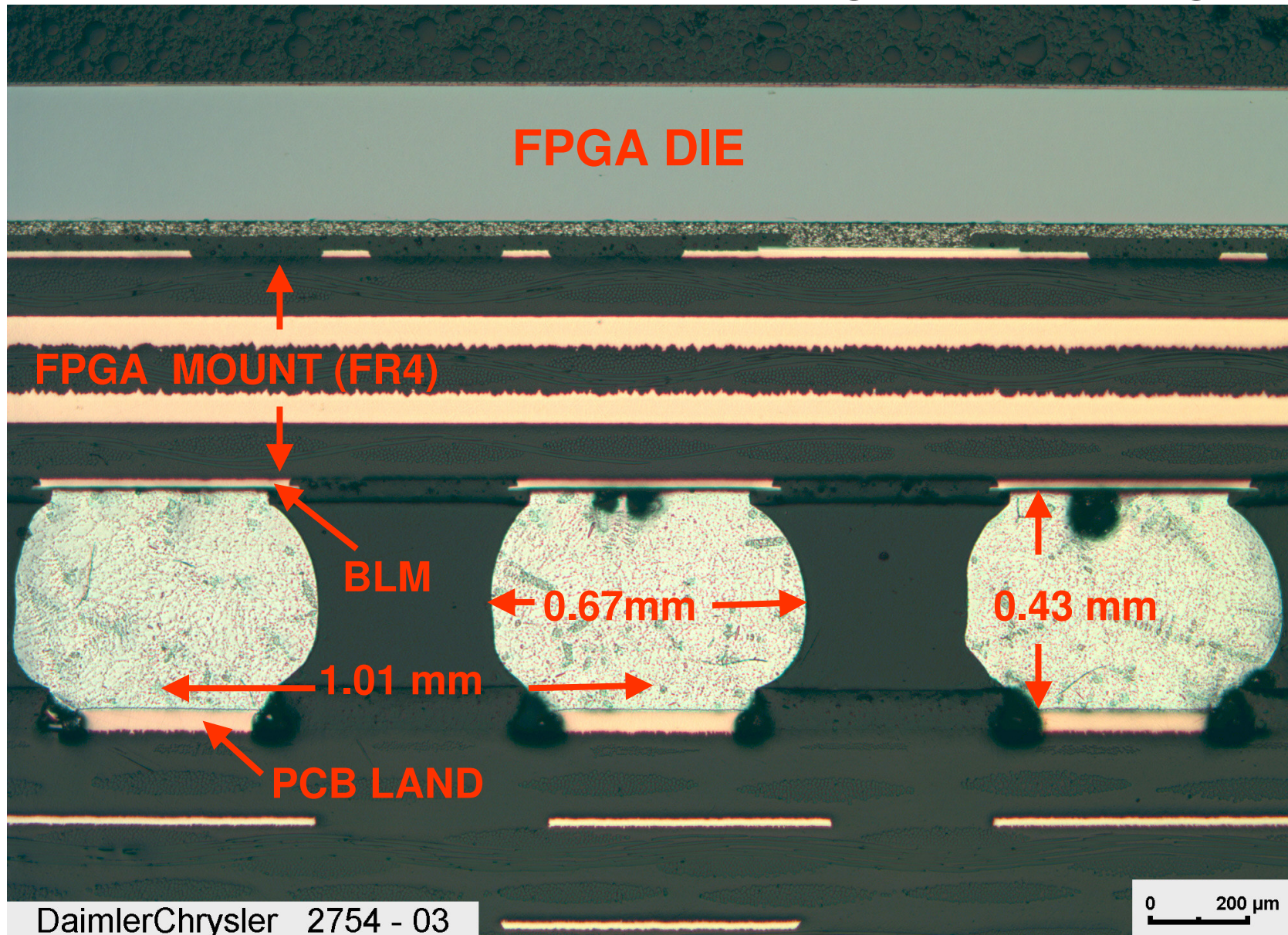
XILINX® FG1156
Die on mounting base



34x34 array of pins
35mm square – bottom of
the base (package)

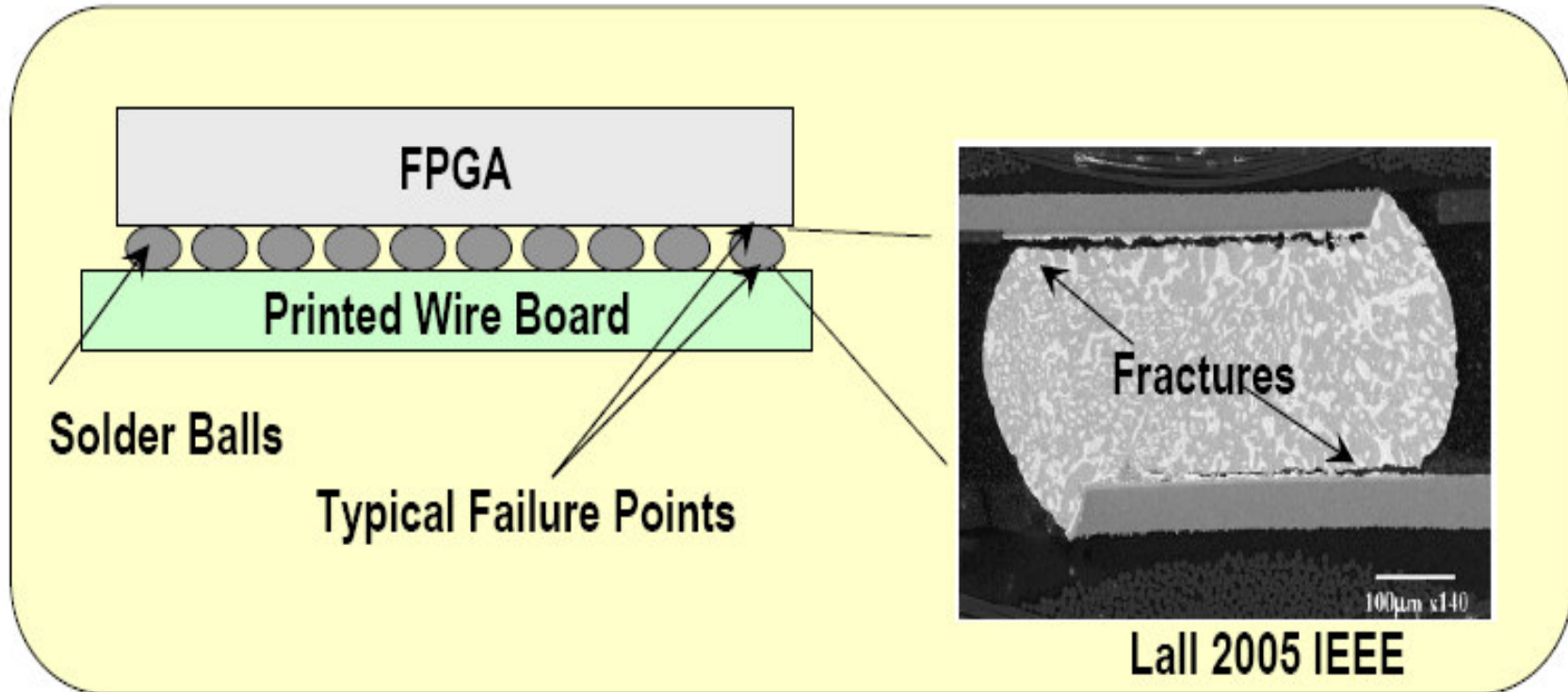


State of the Art: BGA Mounting and Soldering

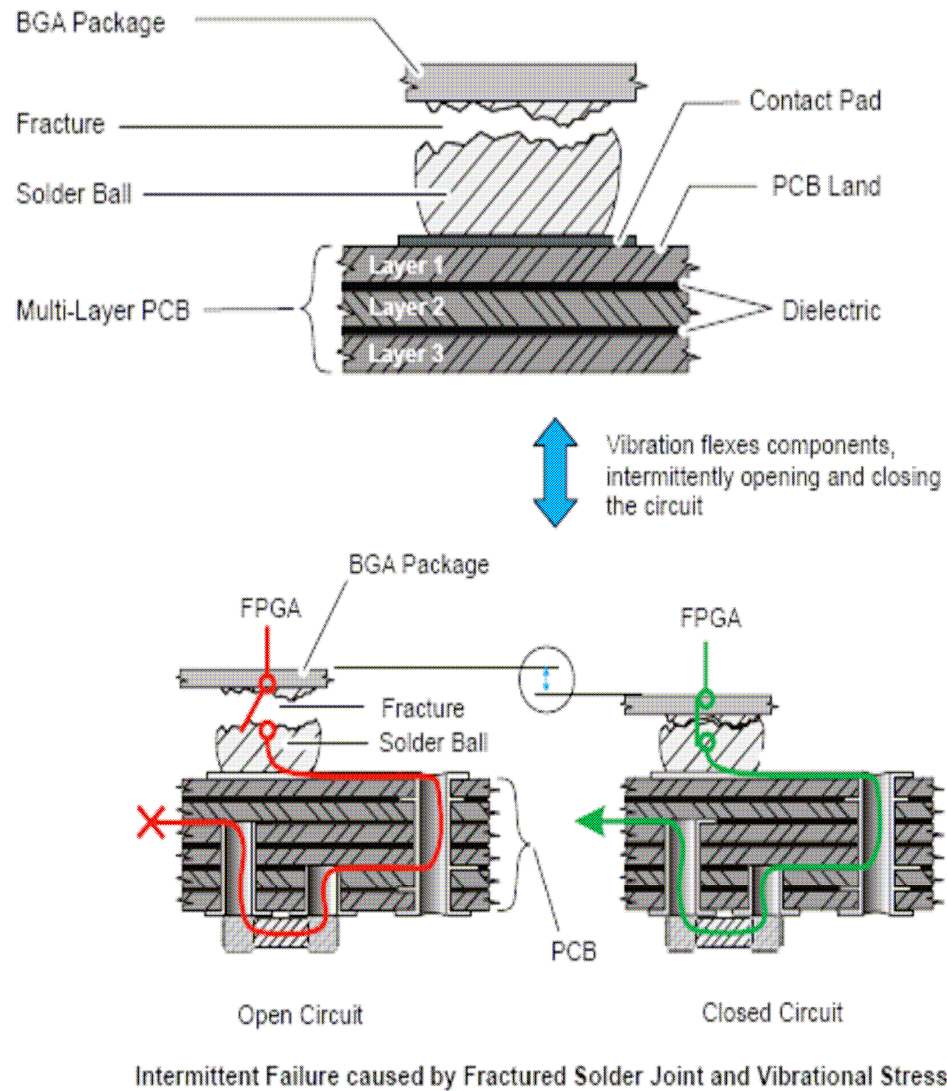


State of the Art: Solder Balls, Cracks and Fractures

- Detects faults in solder-joint networks of FPGAs

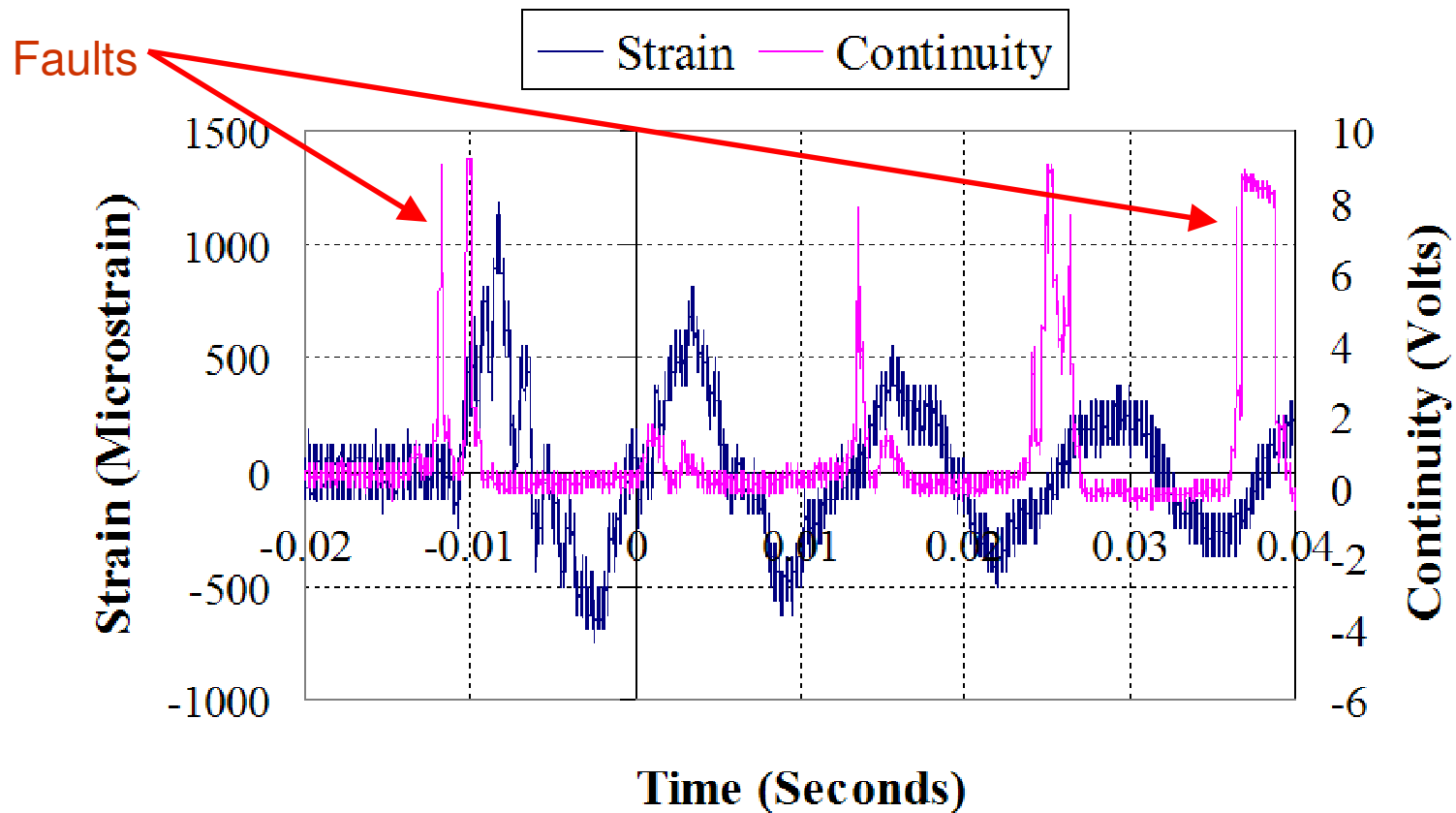


State of the Art: Fractures and Intermittency



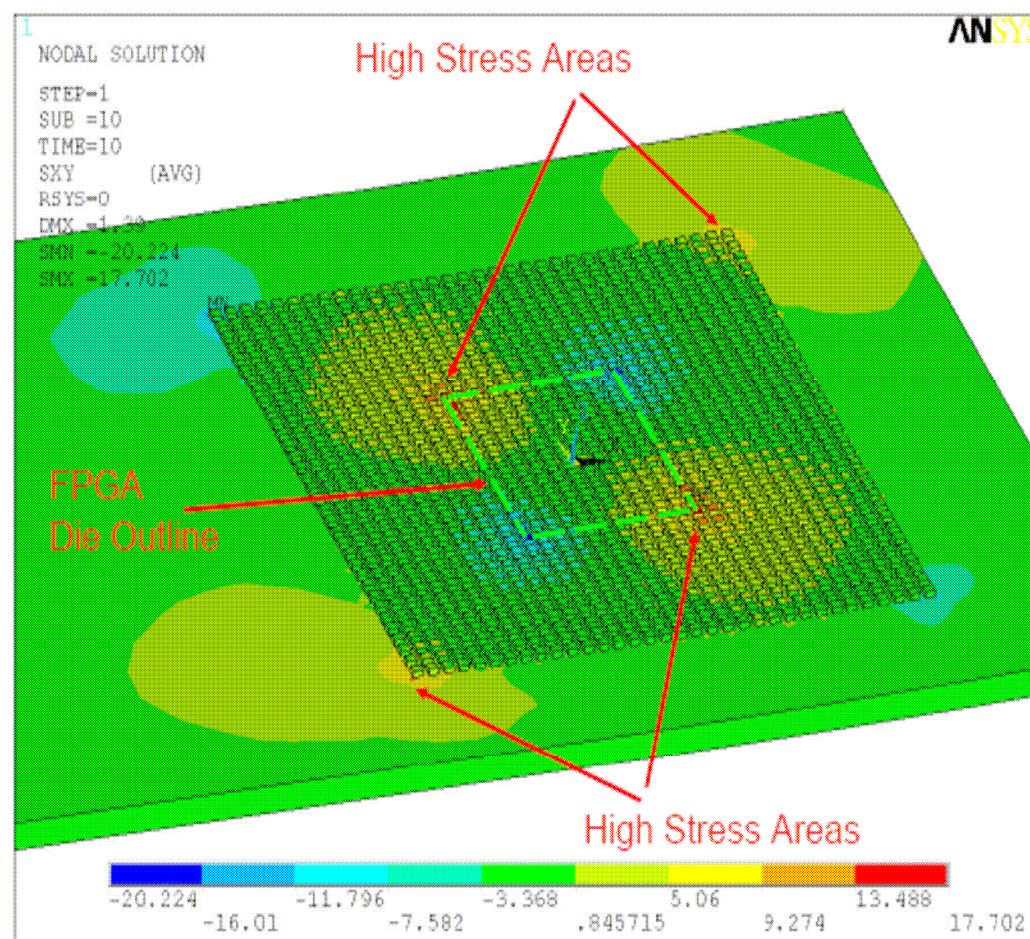
State of the Art: Intermittent Faults in FPGAs

- Faults are intermittent (drop test, CAVE, Auburn Univ.)
 - Occur during periods of increasing strain
 - Multiple occurrences per cycle
 - Industry standard: 200 ϕ +, 200 ns +



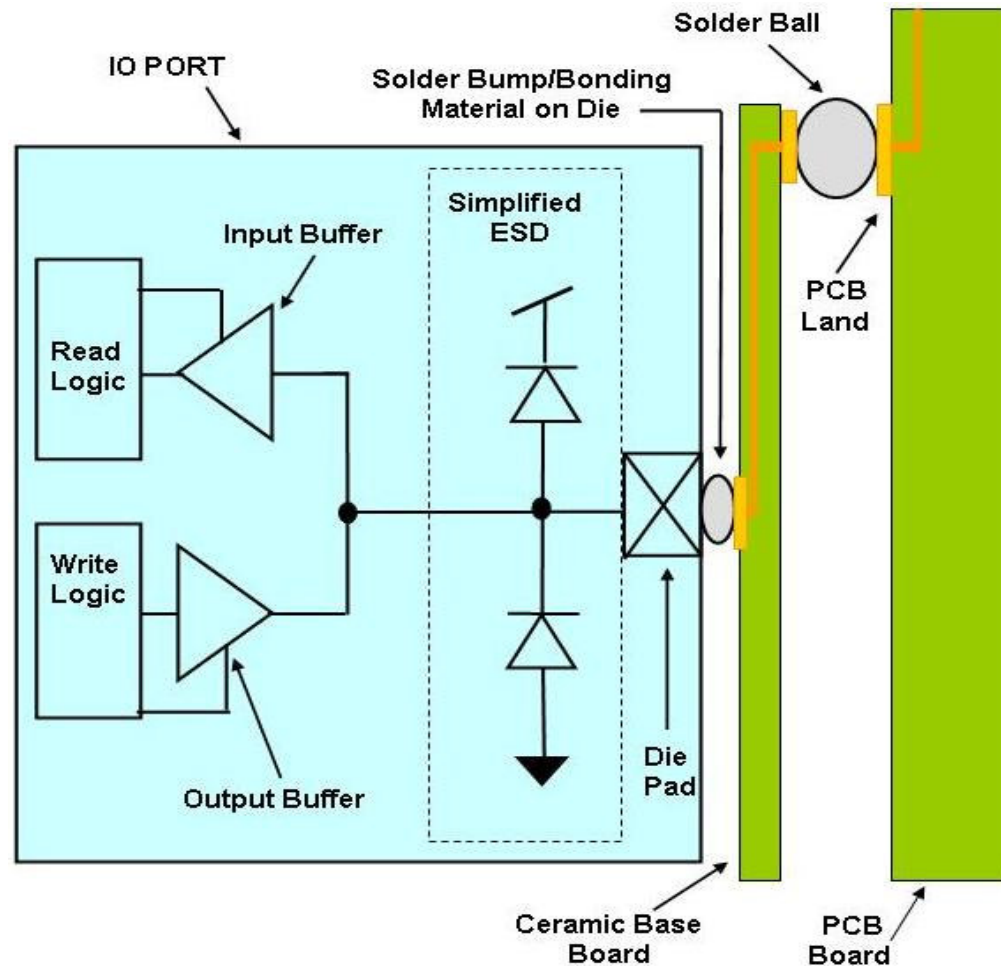
State of the Art: High Stress Areas

- Corner pins likely to fail first
 - High stress areas
 - Corners of the FPGA package and the FPGA die



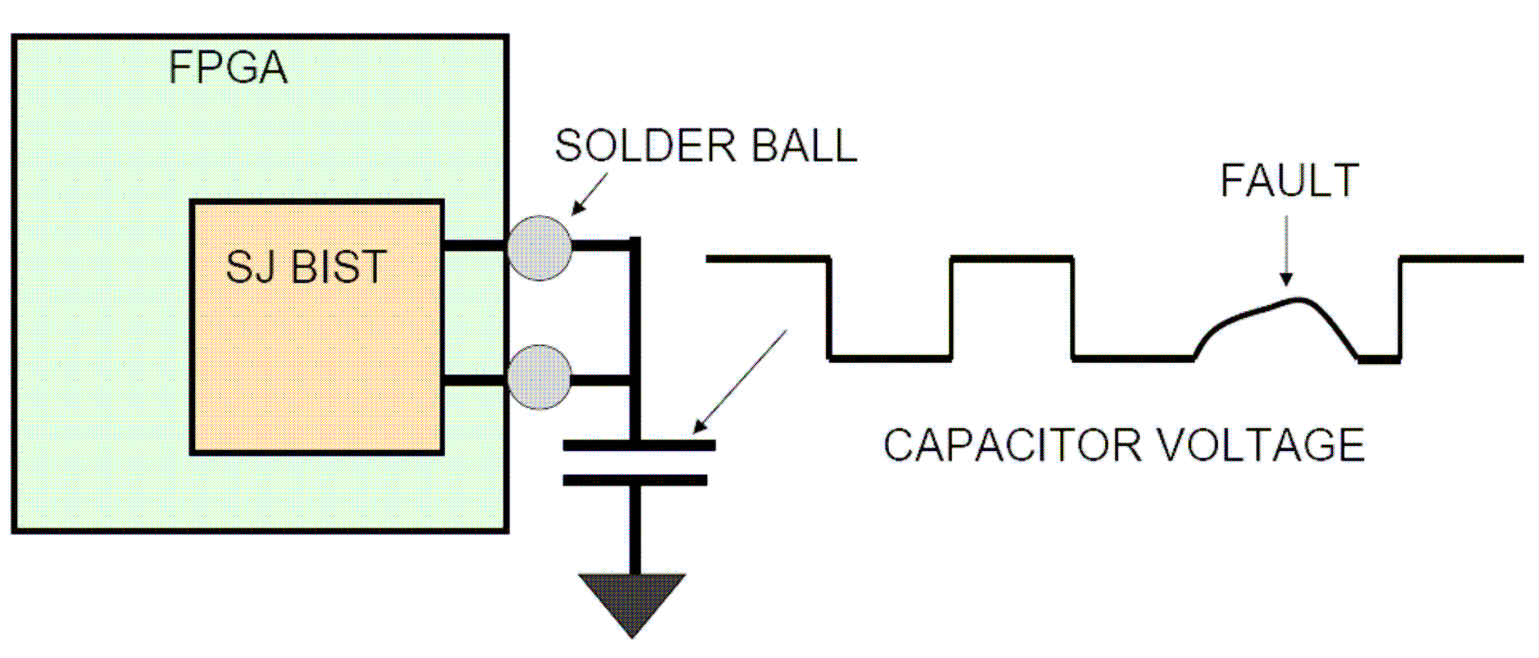
State of the Art: FPGA I/O Ports

- I/O ports are not amenable to direct measurement
 - No direct path to ground
 - Ports are powered



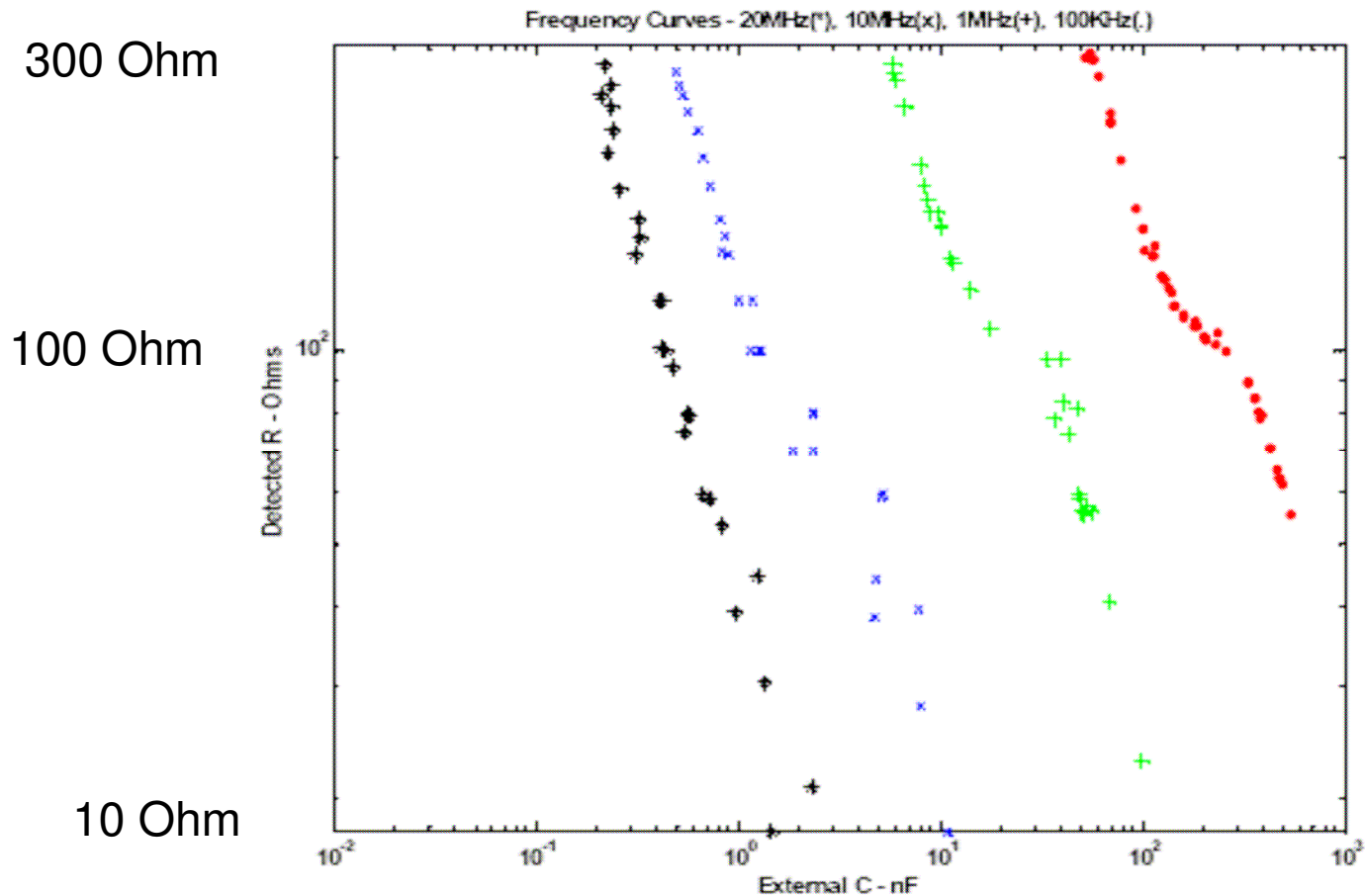
SJ Built-in-Self Test™ (SJ BIST™) - Fault Sensor

- Verilog firmware core (patent pending)
 - Each core tests two I/O pins
 - Pins are externally wired together
 - Small capacitor connected to the two pins



SJ BIST™ - CLK, Capacitor, Detectable Fault Resistance

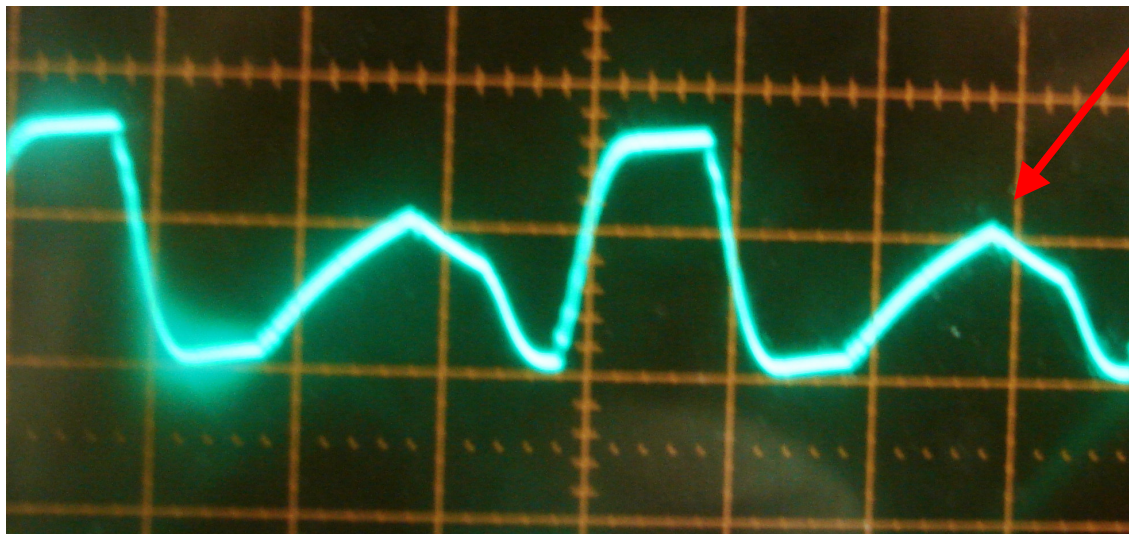
- No false alarms, detection dependent on
 - Operating clock frequency and capacitor value
 - Desired sensitivity



SJ BIST™ - Ridgetop Group Test Result

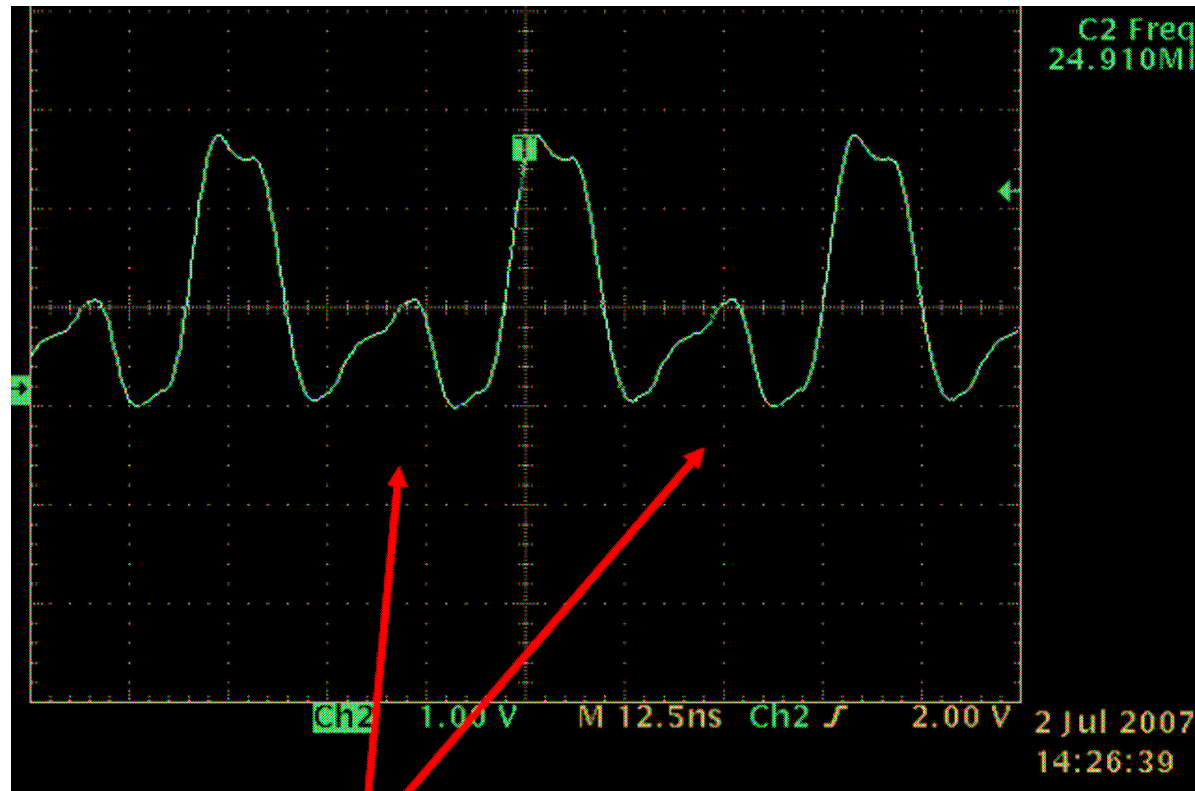
- SJ BIST specifications
 - Sensitivity: as least as low as 100 ϕ
 - Resolution: guaranteed two clock periods
 - Detectable as short as $\frac{1}{2}$ of a clock period
 - 50 MHz clock
 - 40-ns guaranteed detection
 - 10-ns detection possible

100 ϕ fault
1 MHz clock



SJ BIST™ - Daimler and CAVE Test Result

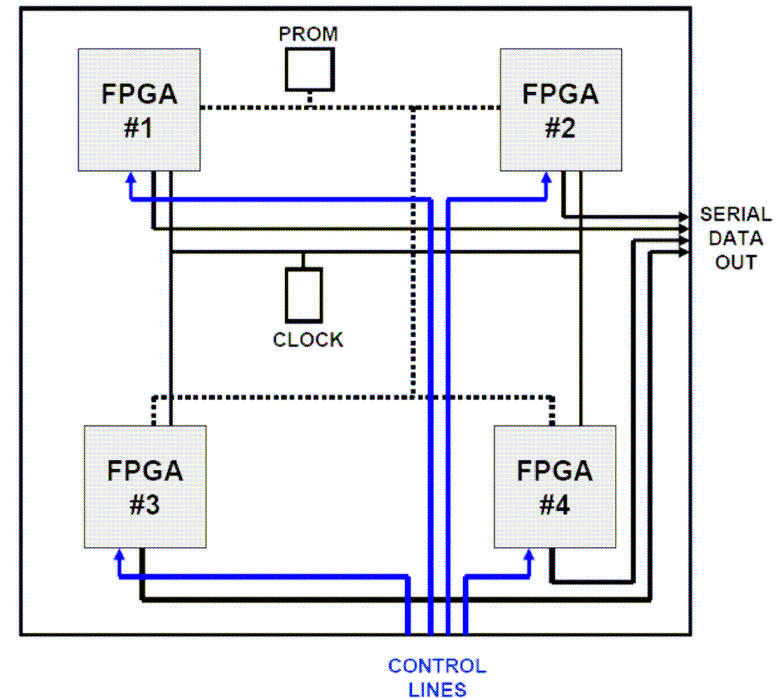
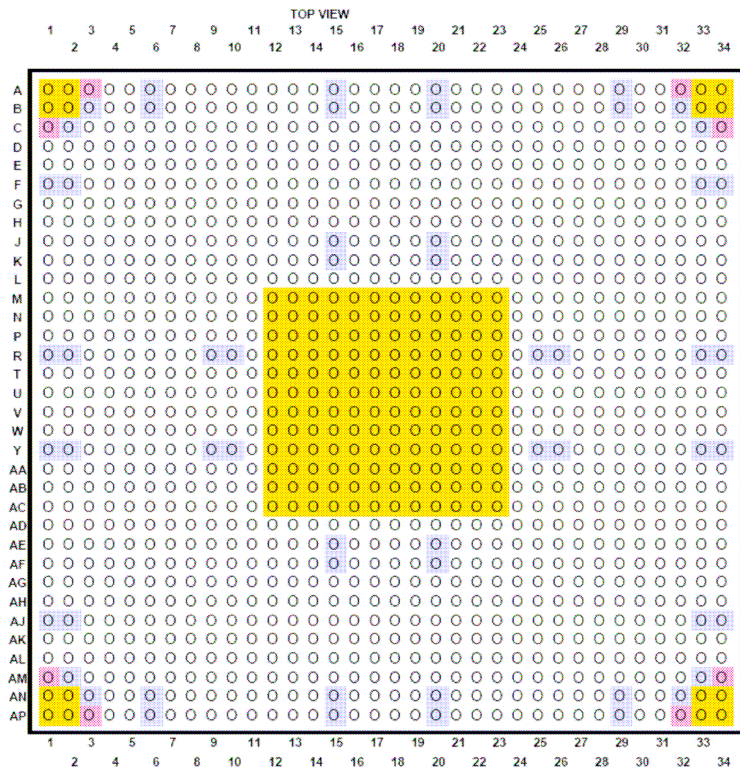
- Independent test results
 - Same as obtained by Ridgetop Group
 - No false alarms



300 Ohm Fault

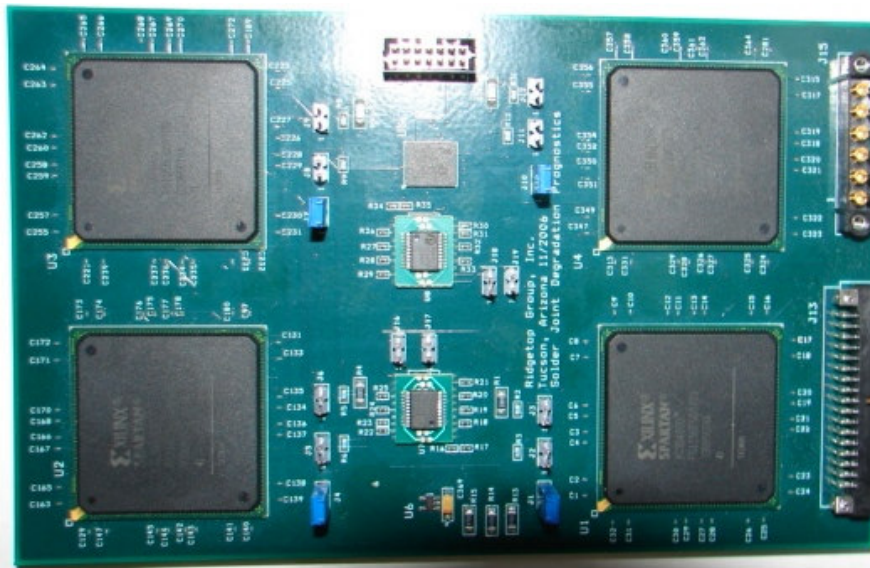
SJ BIST™ - HALT Design of Experiment

- HALT test boards
 - 32 core groups, 64 test pins per FPGA (shaded pins)
 - 4 FPGAs on each board
 - 4 boards
 - Orange: reserved use by XILINX



SJ BIST™ - HALT Board, Demo Box

- TRL 7 – Licensing Ts & Cs are available
 - HALT testing at 2 non-Ridgetop locations
 - Demonstration box for evaluation by missile manufacturer



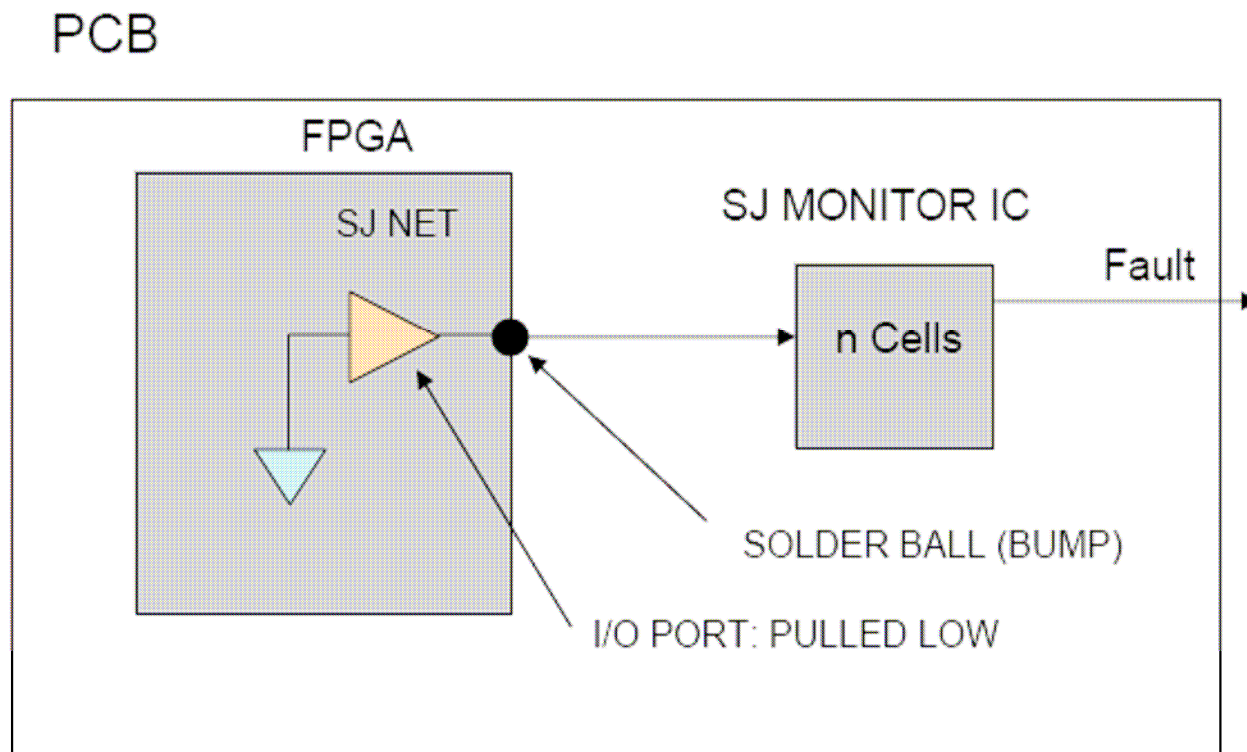
HALT board



Demonstration box

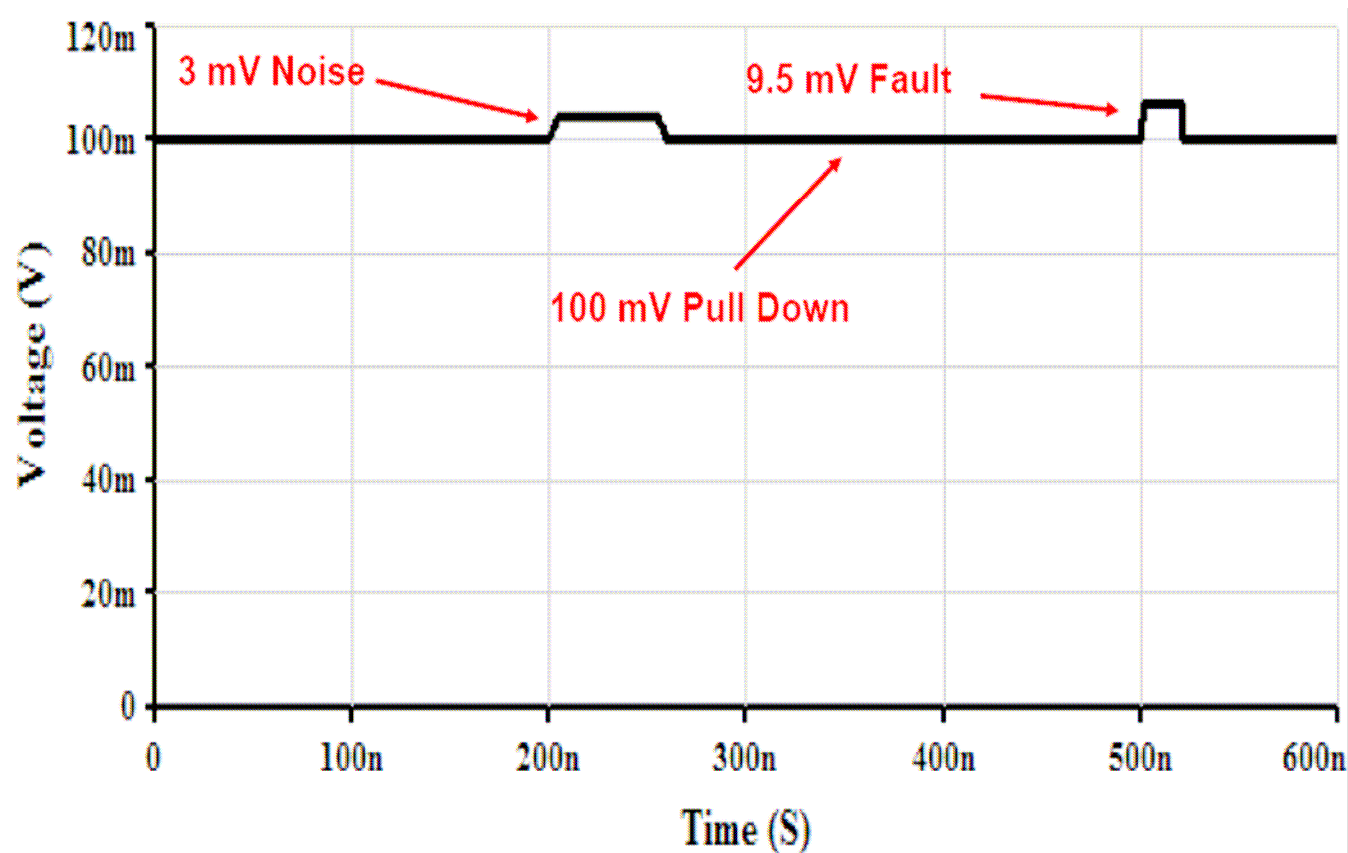
SJ Monitor™

- SJ Monitor™ block diagram (patent pending)
 - Faults in solder-joint pins of FPGAs are intermittent in nature
 - Low power design for use as a 24x7 monitor
 - IC chip on same board as FPGA
 - Complementary circuit will test powered off FPGA



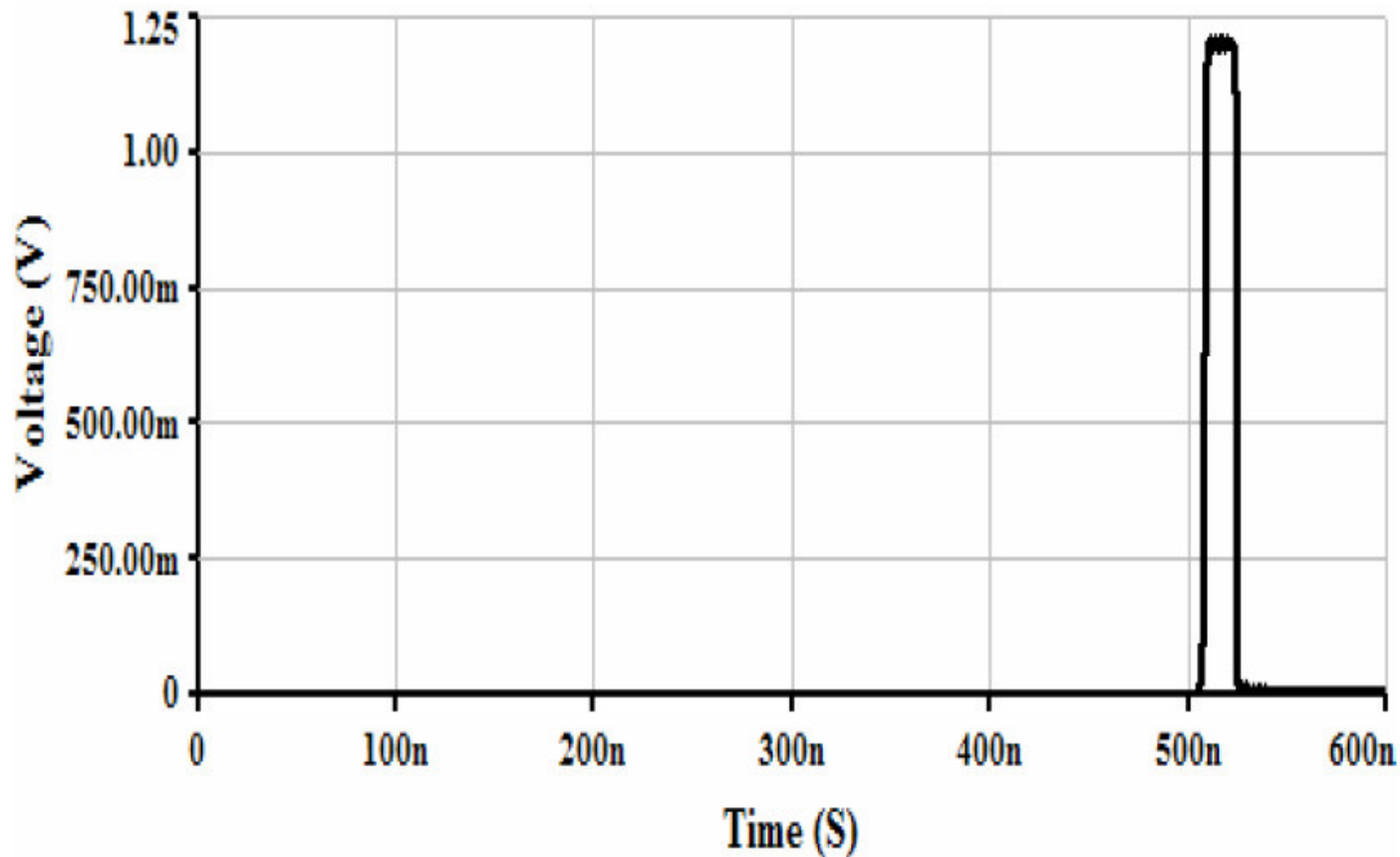
SJ Monitor™

- I/O pin signals
 - Insensitive to pull-down Voltage: 0 to 300 mV
 - Input signal-to-noise ratio: 3.2



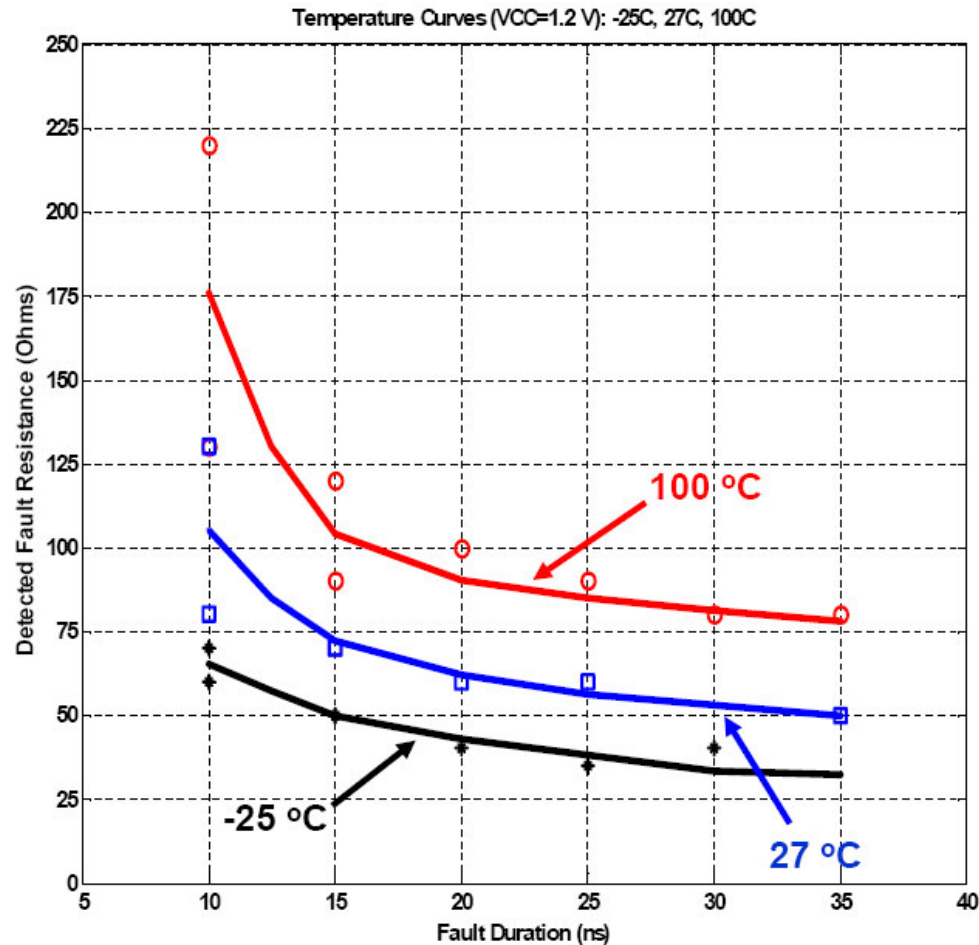
SJ Monitor™

- Signal conditioned
 - Digital '1' when fault is detected
 - Noise suppressed to less than 1 mV



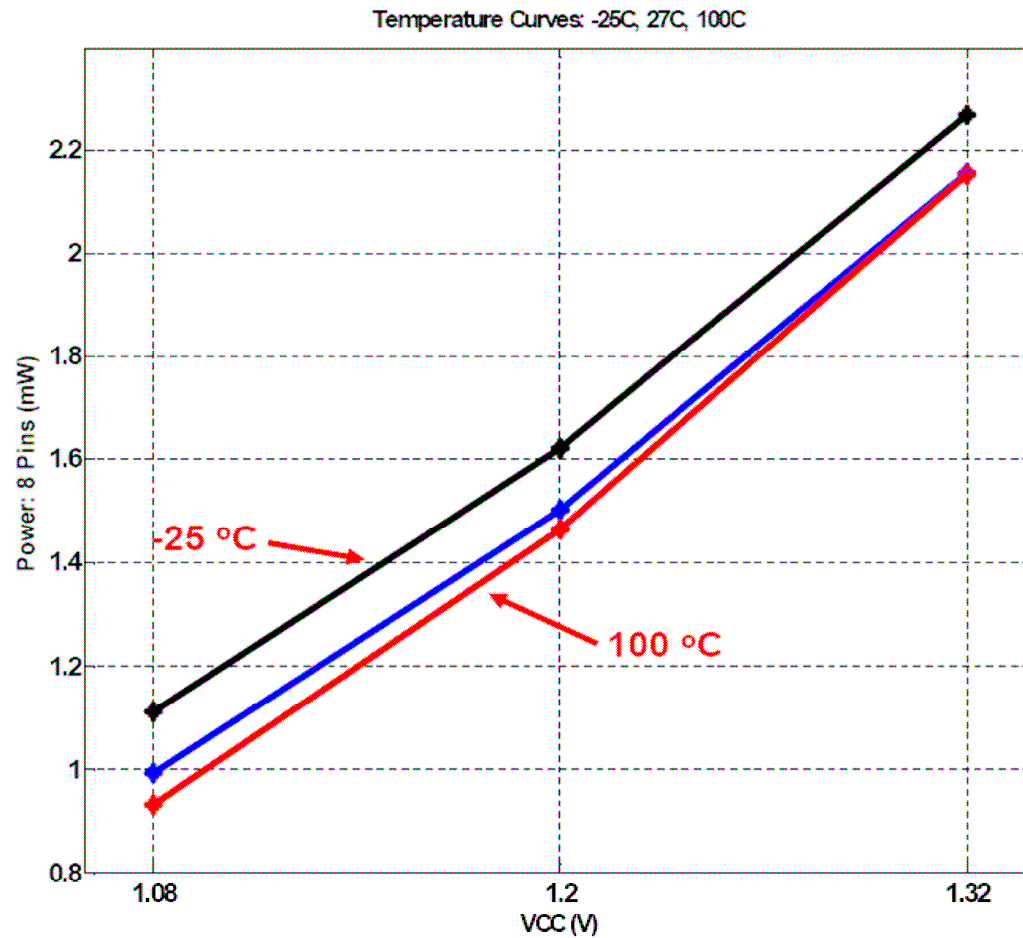
SJ Monitor™

- Fault detection
 - At least as low as 100 Ohm
 - At least as short as 15 ns



SJ Monitor™

- Low power IC:
 - Between 0.9 and 2.4 mW



SJ BIST™ - Deliverables

Sales Fact Sheet: NC, available now

Data Sheet: NC, available now

Installation and Use Guide: Licensed material

Limited support and engineering service hours

per license agreement

and/or negotiated agreement

Demonstration Box – Purchase

part of price can be applied to license

user manual

does not include Installation and Use Guide

SJ Monitor™ - In Development and Test

Design and Development

IBM 130-nm 8RF bulk CMOS, 1.2 V

Analog circuit design: complete

Digital circuit building blocks: complete

Simulations: complete (corner, temp, power)

Digital subset

IC Layout and Masks

DRC, LVS complete – taped out Sep. 2007

Required Tasks to Reach TRL 6 (Phase II Option)

Layout and mask entire sensor

Layout and pad IC chip (4 or 8 sensors/chip)

Fabricate, package and perform verification testing

Characterization and HALT testing

Silicon Validation, Data Sheet, License Ts & Cs